

ABSTRACT OF DISCLOSURE

A method of surface-mounting a semiconductor chip on a PCB, for mounting a flip chip type semiconductor chip on the PCB mounted with electronic components, that includes forming a solder bump on a conductive contact area of each semiconductor chip on a back of a semiconductor wafer mounted with a plurality of semiconductor chips, injecting underfill material on the area of the semiconductor wafer formed with the solder bump, partially hardening the underfill material to have cohesive properties, severing the semiconductor wafer into a plurality of individual semiconductor chips, arranging the severed semiconductor chips having the hardened underfill material on the PCB, and heating the PCB with a predetermined temperature. The present invention provides the surface-mounting method of the semiconductor chip having a simplified process by removing the need to have a package for the semiconductor chip transfer in the middle of the process, and not requiring strict tolerances for the minimum distance between the electronic components.